

# CnC Tech

Industrial Cable and Connector Technology

## CnC Tech Soldering Recommendations for the 3X10, 3X20, and 3221 Series

Recommended temperature and time periods for the soldering process

Series	Soldering Method	Temperature in the furnace (lead-free)	Plastic	Furnace time	Soldering time
3020-XX-0100-00	wave	235°C ± 5°C	9T	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3020-XX-0200-00	wave	235°C ± 5°C	9T	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3020-XX-0300-00	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3020-XX-0300-00-TR	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3220-XX-0100-00	wave	235°C ± 5°C	9T	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3220-XX-0200-00	wave	235°C ± 5°C	9T	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3220-XX-0300-00	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3220-XX-0300-00-TR	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3221-XX-0100-00	wave	235°C ± 5°C	9T	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3221-XX-0200-00	wave	235°C ± 5°C	9T	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3221-XX-0300-00	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3221-XX-0300-00-TR	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3010-XX-001-12-00	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
3010-XX-001-13-00	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
3010-XX-002-12-00	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
3010-XX-002-13-00	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
3010-XX-003-12-00	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3010-XX-003-13-00	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3210-XX-003-12-00	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3110-XX-003-11-00-TR	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3110-XX-003-12-00-TR	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3110-XX-003-13-00-TR	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3110-10-001-11-00	wave	235°C ± 5°C	9T	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3110-10-001-12-00	wave	235°C ± 5°C	9T	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3110-10-001-13-00	wave	235°C ± 5°C	9T	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec

# Reflow Soldering

## Solderability Profile

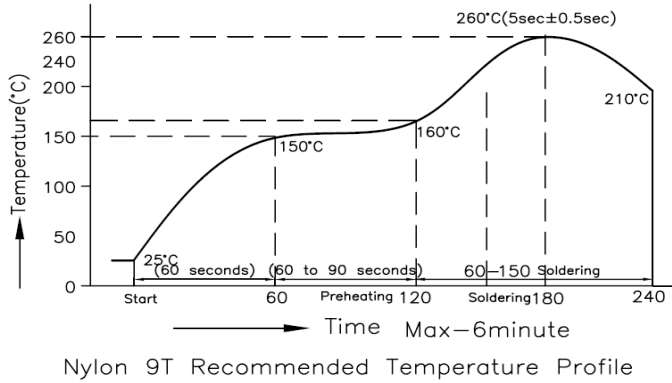
Sub=Nylon 9T Material Temperature Specification

Solder regular Condition

- 1) Soldering temp: 260°C ± 5°C
- 2) Time: 5 ± 0.5 sec
- 3) Solder wetting percentage: 95% min

Reflow Condition

Test Conditions



- 1) Solder Method: Reflow or Wave
- 2) Environment: Room air
- 3) Solder Composition: Soldering Paste
- 4) Test Board: 52mmX36.5mmX1.6mm thick
- 5) This temperature profile is based on the above conditions. Individual applications the actual temperature may vary. Consult your solder paste and equipment manufacturer for specific recommendations
- 6) There must not be visible defect after testing

# Wave Soldering

## Solderability Profile

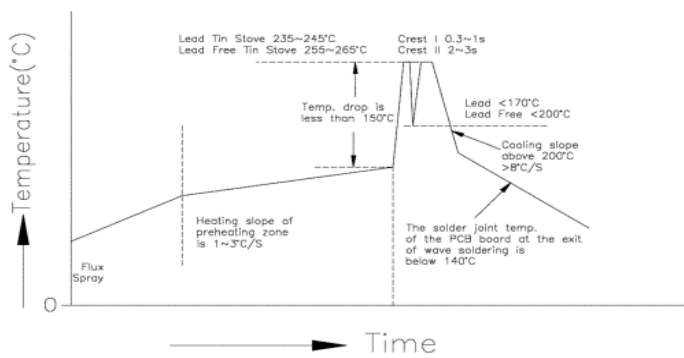
Temperature Specification

Solder regular Condition

- 1) Lead tin stove 235~245 °C  
Lead Free tin stove 255~265 °C
- 2) Time: 5 ± 0.5 sec
- 3) Solder wetting percentage: 95% min.

Wave Soldering Condition

Neltron Test Conditions



- 1) Solder Method: Wave
- 2) Environment: Room air
- 3) Solder Composition: Soldering Paste
- 4) Test Board: 52mmX36.5mmX1.6mm thick
- 5) This temperature profile is based on the above conditions. Individual applications the actual temperature may vary. Consult your solder paste and equipment manufacturer for specific recommendations
- 6) There must not be visible defect after testing